



# SOT650-2

plastic thermal enhanced very thin small outline package; no leads; 10 terminals; 3 x 3 x 0.85 mm

23 November 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HVSON10
<b>Package type industry code</b>	HVSON10
<b>Package style descriptive code</b>	HVSON (thermal enhanced very thin small outline; no leads)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-229
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-03-2009
<b>Manufacturer package code</b>	SOT650

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
seated height	-	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	10	-	



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## 2 Package outline

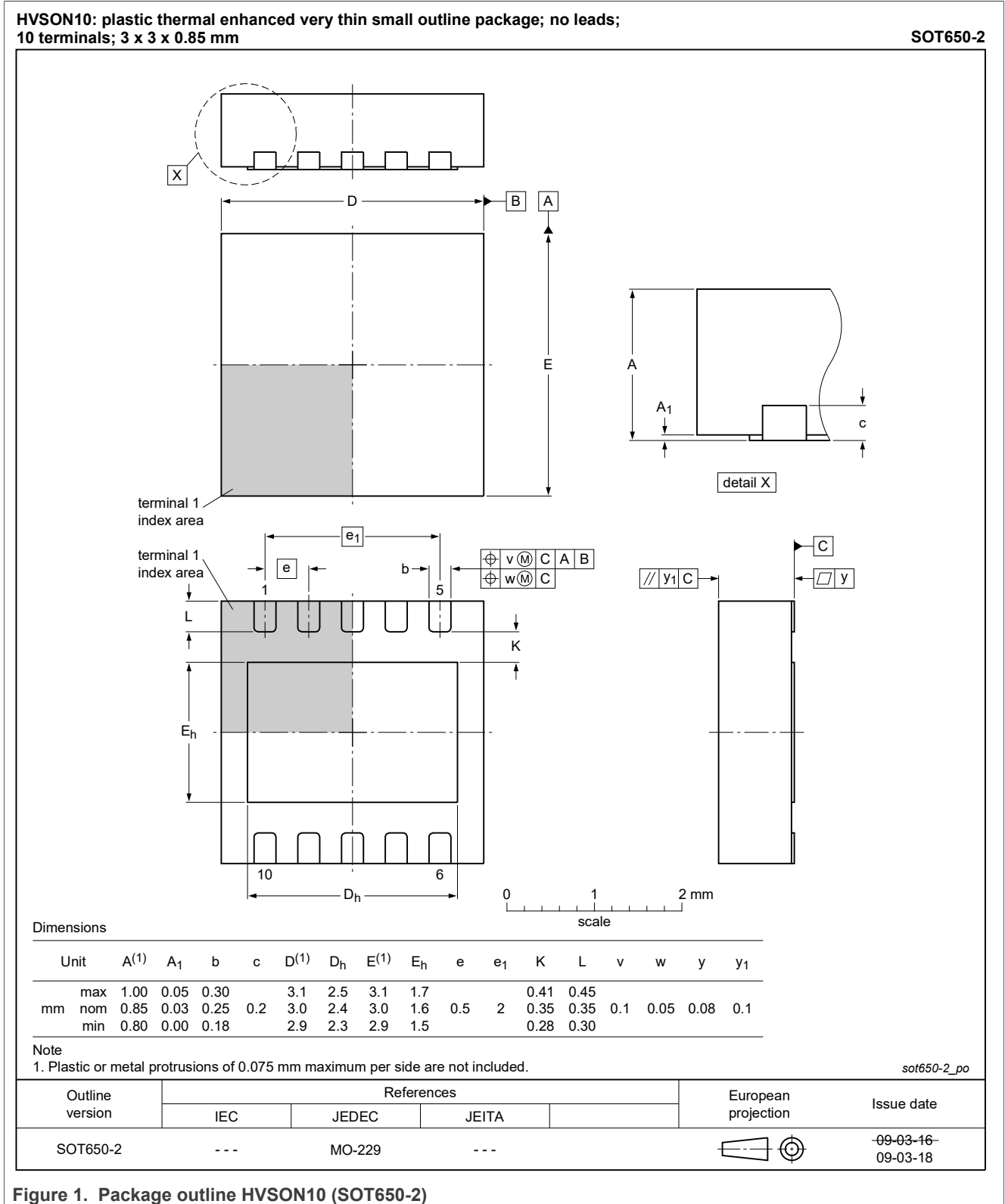
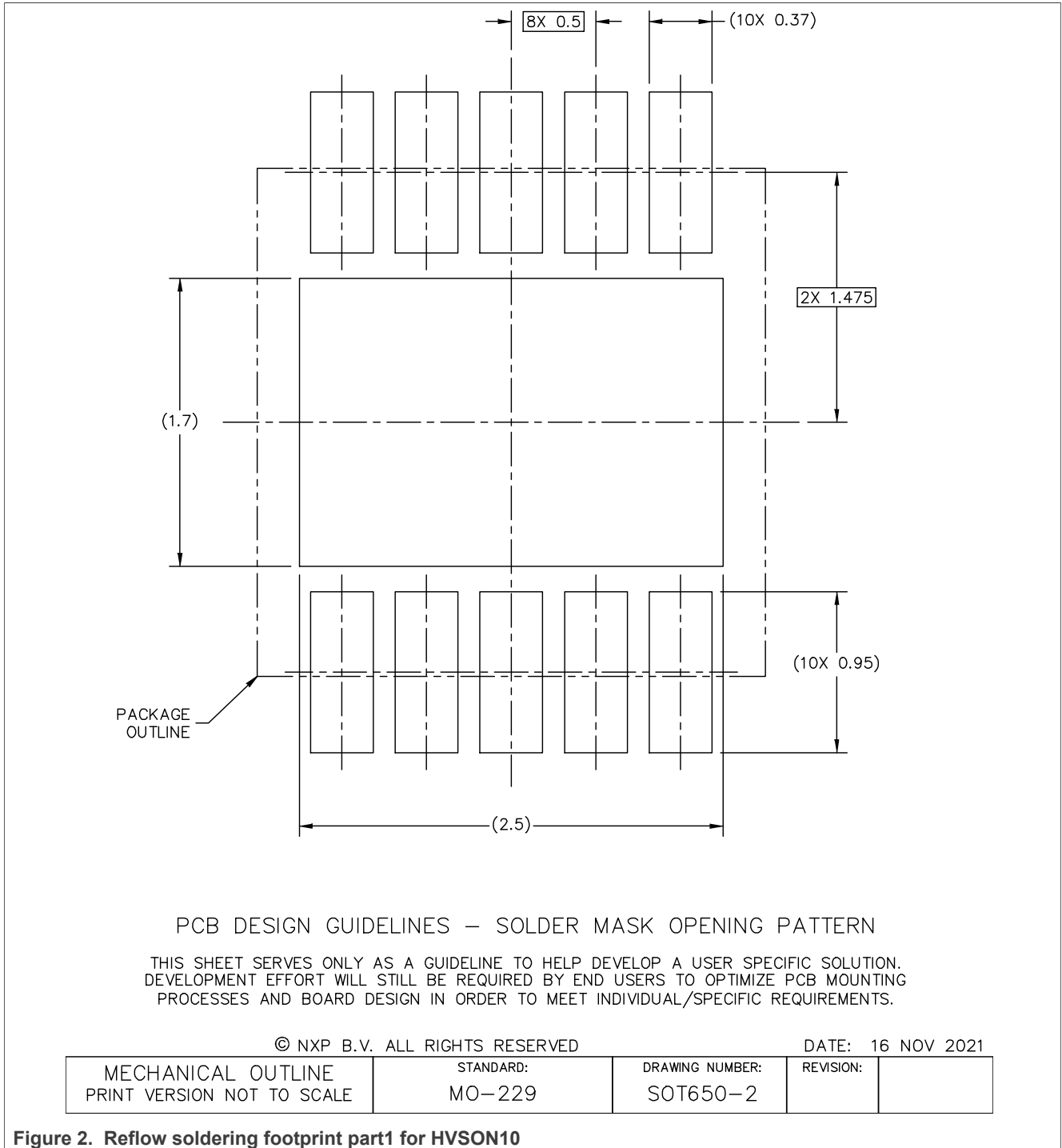
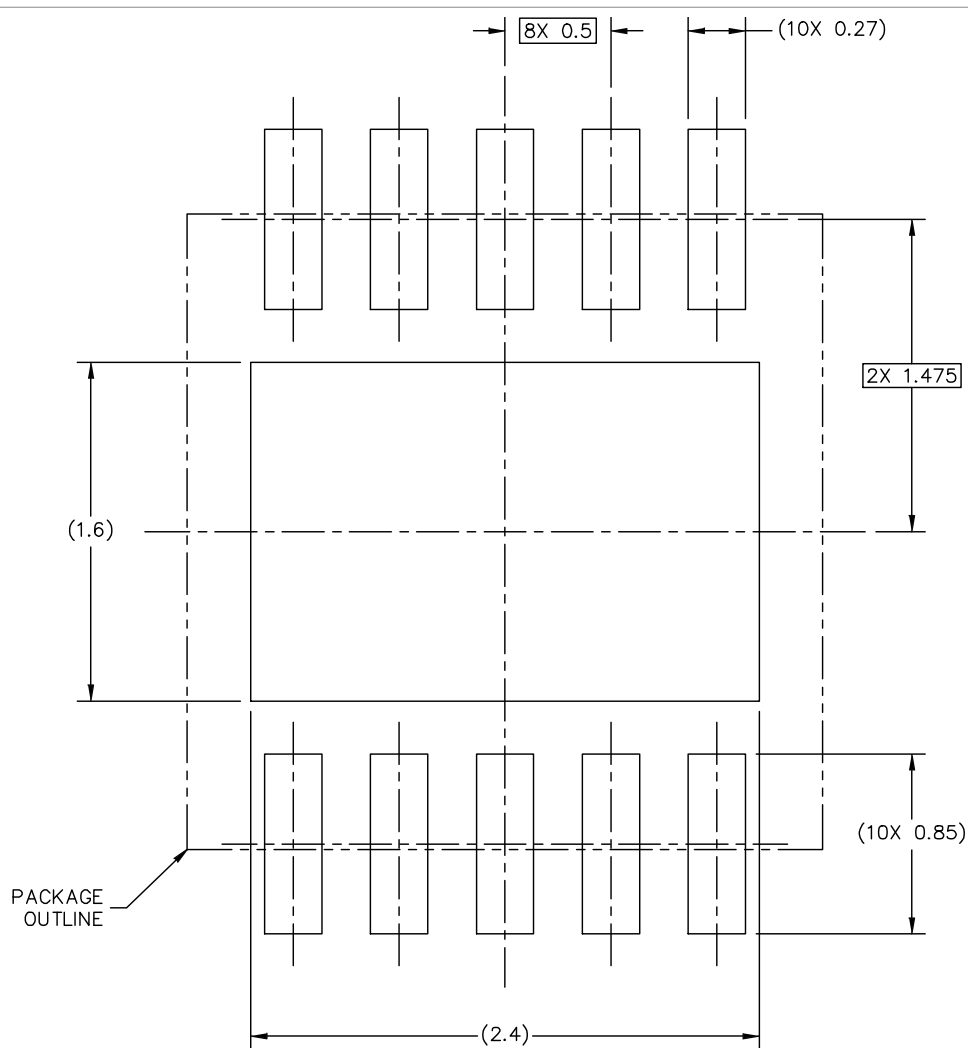


Figure 1. Package outline HVSON10 (SOT650-2)

### 3 Soldering



plastic thermal enhanced very thin small outline package; no leads; 10 terminals; 3 x 3 x 0.85 mm



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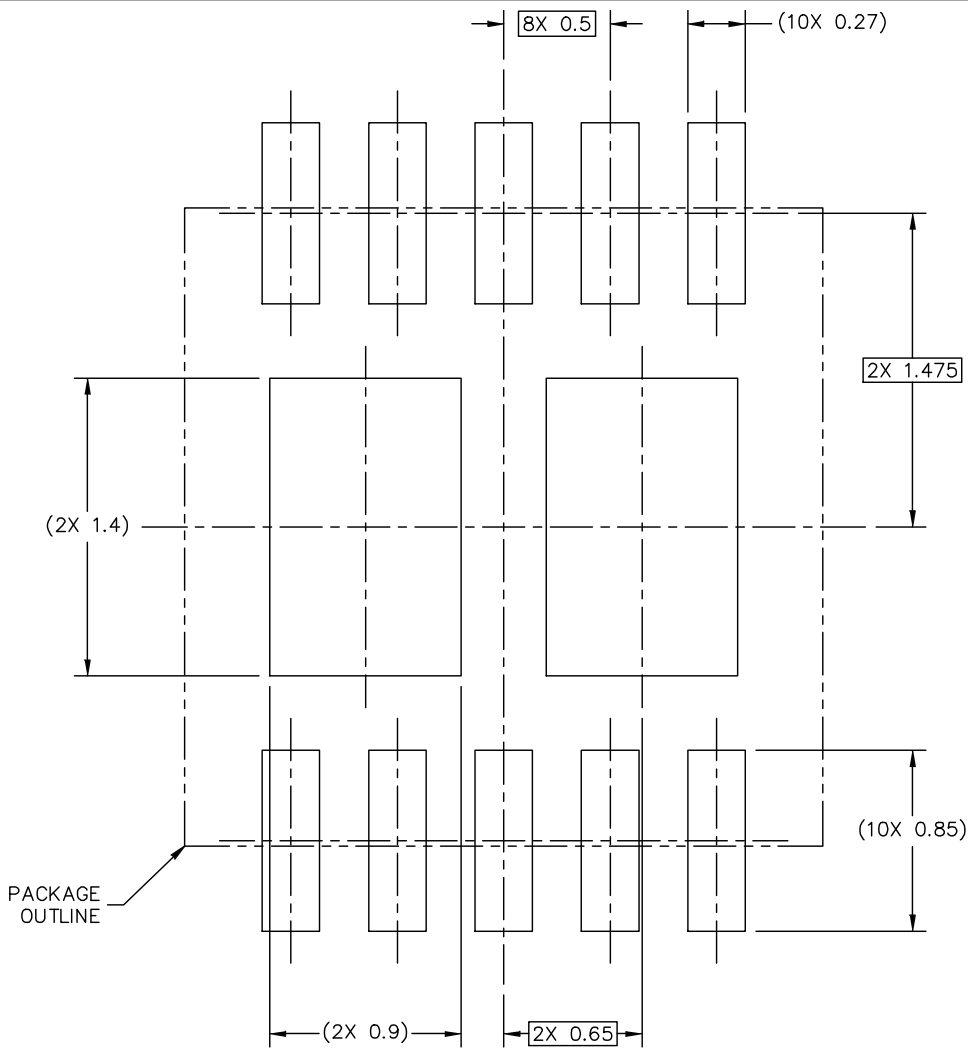
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DATE: 16 NOV 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-229	DRAWING NUMBER: SOT650-2	REVISION:	
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Figure 3. Reflow soldering footprint part2 for HVSON10

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for HVSON10

## 4 Legal information

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**Contents**

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1 Package summary .....1  
2 Package outline .....2  
3 Soldering .....3  
4 Legal information .....6